

SHENZHEN SHOUHAN TECHNOLOGYCO.,LTD

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承 认 书

SPECIFICATION FOR APPROVAL

轻触开关		
TS263065A 330gf (7.5) MSM BD Membrane Switch		

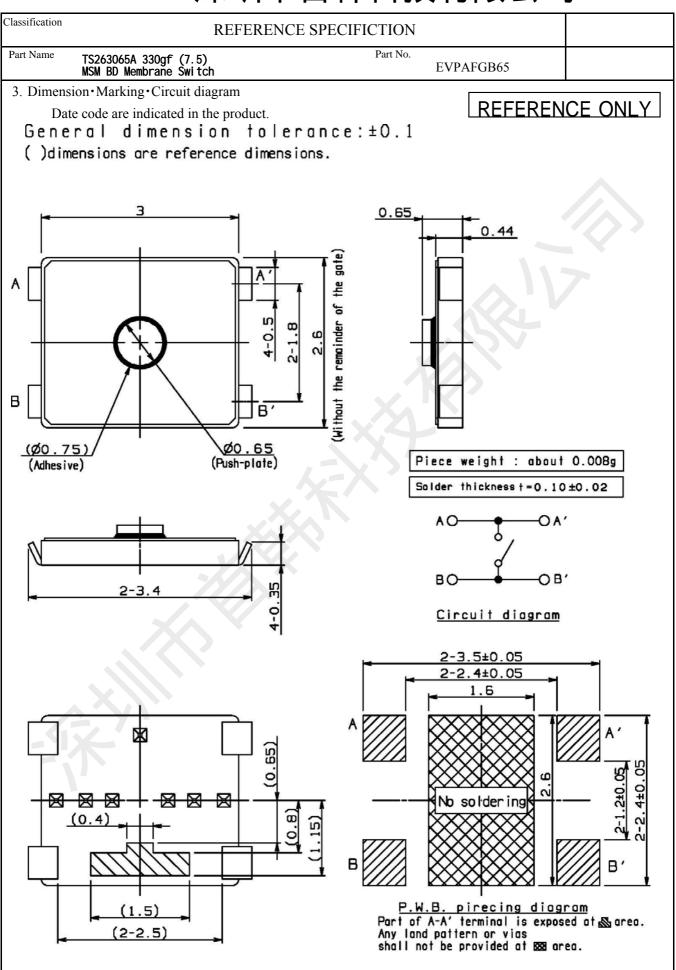
贵公司承认印 Approval signatures

料 号/Part No.	签 章/Signatures

日期 Date:

拟制/Drawn	李春风	《岩蘭科技有图》
审核/Check	钟华华	AND HAVE BUILD
批准/Approved	罗孝金	工程专用草







Classification	REFE	RENCE SPECIFICATION	
Part Name	TS263065A 330gf (7.5) MSM BD Membrane Switch	Part No. EVPAFGB65	

4. General specification

4.1 Switch rating DC 15 V 20 mA(max.) DC 2 V 10 μ A(min.)

4.2 Operation temperature range $-40 \sim +85 \, ^{\circ}\text{C}$

4.3 Preservative temperature range Single condition : - 40 \sim + 85 $^{\circ}$ C

Taping condition: - 20 \sim + 60 $^{\circ}$ C

4.4 Standard conditions

Unless otherwise specified, the test and measurements shall be carried out as follows.

Ambient temperature : 5 \sim 35 $^{\circ}$ C Relative humidity : 45 \sim 85 $^{\circ}$ C Atmospheric pressure : 86 \sim 106 kPa

However, if doubt arises on the decision based on the measured values

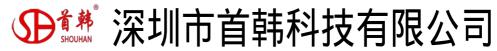
under the above-mentioned conditions, the following conditions shall be employed.

Ambient temperature : 20 ± 2 °C Relative humidity : 65 ± 5 % Atmospheric pressure : $86 \sim 106$ kPa

5. Performance

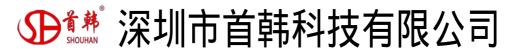
5.1 Electrical characteristics

No.	ITEM	TEST CONDITION	PERFORMANCE
5.1.1	Contact	Push force : $\{\text{Operation force}\} \times 2$	500 mΩ max.
	resistance	Measurement tool : Contact resistance meter	
		(Capable of 10 μ A \sim 10 mA)	
5.1.2	Insulation	DC 100 V (Between terminals)	50 MΩ min.
	resistance		
5.1.3	Withstand	AC 250 V for 1 minute. (Between terminals)	No insulation
	voltage		destruction
5.1.4	Bouncing	Operation speed: 3~4 times/s D. C. 10V 10k0 Oscillo scope Switch Bouncing Test Circuit	ON 10 ms max. OFF 10 ms max.



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	M2W RD WEMBLANE	SWITCH EVPAFGB65	
5.2 Me	chanical characteris	tics	
No.	ITEM	TEST CONDITION	PERFORMANCE
5.2.1	Operation force	Operation feeling shall be measured after	Push force
0.2.1	operation force	3 times pre-operations.	1.6 + 0.5 N
		Pre-operation condition :3 times, 1mm/s by 3 N	1.0 - 0.5 ^{IN}
		Measurement speed: 0.5 mm/s	
		Λ <u>φ2.99</u> →	Return force
		Push force Ø3.0	0.1 N min
		Return force	
		Switch	
		Stroke ——> Fig. measuring jig	
5.2.2	Travel to	1 F	
	closure		0.15 ⁺ 0.1 mm
		Travel	- 0.1
		Travel to closure	V
5.2.3	Click ratio	Stroke —> Measurement condition:No.5.2.1	Click ratio
3.2.3	Click fatio	X [30 % min.
		Push force(a)	(before reflow soldering)
		(c) Return force(b)	(before fellow soldering)
		Kerdini Torce(b)	
		Stroke —— Click ratio = (a-c)/a×100%	
5.2.4	Push strength	50 N for 15 sec.	No damage
3.2.4	Pusii stiengtii	, 90°	(Electrical and
		u L	mechanical
5.2.5	Cido much	3 N, 15 sec.	·
3.2.3	Side push	Initial product with	No damage
	strength	(Electrical and	
		mechanical	
526	Vilonotion toot	(Reflow condition: see 6.1)	No. 5.1 and
5.2.6	Vibration test	1) Amplitude : 1.5 mm	No.5.1 and
		2) Sweep rate : 10-55-10Hz for 1 minute	5.2.1 to 5.2.2 shall
		3) Sweep method : Logarithmic frequency	be satisfied.
		sweep rate	
		4) Vibration direction : X,Y,Z(3 directions)	
		5) Time : Each direction 2 hours	
		(Total 6 hours)	Contact resistance
5.2.7	Soldering heat	Mount the switch on P.W.B by solder paste.	Contact resistance $500 \text{ m}\Omega$ max.
	test	1) Reflow process 2 times. (Refer to section 6.1)	No.5.1.2 to 5.1.4 and
	-	2) Standard conditions after test: 1 hours	No.5.2.1 to 5.2.2
			shall be satisfied.
5.2.8	Solderbility	After spreading flux, the terminal is immersed	95% or more of surface
		in solder with following condition.	area(Excluding ruptured
		Solder bar : M705/Sn-3.0Ag-0.5Cu	surface)where is
		(Senju Metal Industry Co.,Ltd.)	immersed in solder
		Flux : CF-110VH-2A (tamura kaken)	shall be covered by new
		Soldering temperture : 260±5 °C	solder.
		Soldering time : 2±0.5 sec.	
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	MSM BD Membrane Switch	EVPAFGB65	

No.	ITEM	TEST CONDITION	PERFORMANCE
5.3.1	Cold test	1) Temperature : -40±2 ℃	Contact resistance
		2) Duration of test : 500h	1000 mΩ max.
		3) Take off a drop water.	No.5.1.2 to 5.1.4 and
		4) Standard conditions after test : 1 h	No.5.2.1 to 5.2.2
			shall be satisfied.
5.3.2	Heat test	1) Temperature : 85 ± 2 °C	Contact resistance
		2) Duration of test: 500h	$1000 \text{ m}\Omega$ max.
		3) Standard conditions after test : 1 h	No.5.1.2 to 5.1.4 and
			No.5.2.1 to 5.2.2
			shall be satisfied.
5.3.3	Heat shock	1) Test cycles : 20 cycles	Contact resistance
	test	2) Standard conditions after test : 1 h	1000 mΩ max.
		^ A:+85±2 °C	No.5.1.2 to 5.1.4 and
		/ B:-40±2 °C	No.5.2.1 to 5.2.2
		C:1 hour	shall be satisfied.
		D:5 minutes max. E:1 hour	
		E:1 hour F:5 minutes max.	
5.3.4	Humidity test	1) Temperature : 60 ± 2 °C	Contact resistance
		2) Relative humidity: 90~95 %	1000 mΩ max.
		3) Duration of test : 500 h	No.5.1.2 to 5.1.4 and
		4) Take off a drop water.	No.5.2.1 to 5.2.2
		5) Standard conditions after test : 1 h	shall be satisfied.
5.3.5	Endurance	1) DC 15 V 20 mA Resistance load	Contact resistance
	(Switching	2) Operation speed : $2\sim3$ times/s	20 Ω max.
	action)	3) Push force : Maximum value of operation	Bouncing: 10 ms max
		force	Variation rate of
		4) Operation number : 100,000 times	operation force shall
		, , , , , , , , , , , , , , , , , , , ,	be within ± 30 % to the
			value before testing
			No.5.1.2 and 5.2.2
			shall be satisfied.
5.3.6	Withstand H,S	1) Density : 3±1ppm	Contact resistance
2.2.0	.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	2) Temperature : 40 ± 2 °C	$1000 \text{ m}\Omega \text{ max}.$
	1	1 ′ •	
		1.3) Relative himidity: $20 \sim 25 \%$	1 No 5 1 2 to 5 1 2 and
		3) Relative humidity: 80~85 % 4) Duration of test: 24 h	No.5.1.2 to 5.1.4 and No.5.2.1 to 5.2.2

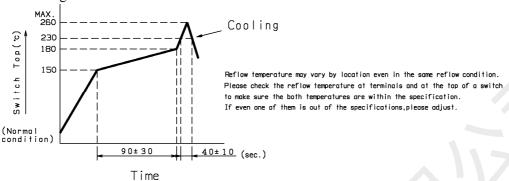


** 深圳市首韩科技有限公司

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Part Name TS263065A 330gf (7.5)
MSM BD Membrane Switch EVPAFGB65

- 6. Prohibitions and precaution for handling
- 6.1 Reflow soldering condition



- 1) Two times max. with directing the switch mounting side of P.W.B up.
- 2) Re-soldering by soldering iron shall be allowed under 350 °C max. 3 sec. max. 1 time only and the tip of iron must not touch to terminals.

 Soldering iron for re-soldering have to be 60 W max.

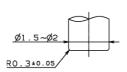
6.2 Design instructions

- 1) Please refer to the land pattern plan Panasonic recommends on the 2nd page.
- 2) Design key top as fig-1.(Recommended operation condition)

As the design of key top may affect operation feeling, please follow the directions stated below.

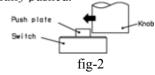
• We recommend to use harder material such as resin for key top, and we do not recommend softer material such as rubber may affect operation feeling.

However in case if you still would like to use softer material, please consult with us beforehand.





- Considering decentering between switch and key top, the key top shall be always positioned to be able to push the entire top surface of actuator.
- Please design housing and key top not to produce friction to each other to avoid inhibition of operation feeling.
- 3) Please design your knob not to hit the switch film or case even when the switch is fully pushed.
- 4) Please pay attention not to add side force (static or impact) to the push plate of the switch, especially when the switch is being built into the products (fig-2)

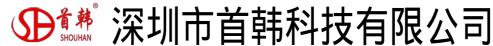


6.3 Note

- 1) Please be cautions not to give excessive static load or shock to switches.
- 2) Please be careful not to pile up P.W.B. after switches were soldered.
- 3) Preservation under high temperature and high humidity or corrosive gas should be avoided especially. When you need to preserve for a long period, do not open the carton.
- 4) Avoid pressing the film portion of the product with sharp-edged object.
- 5) Cleaning
 - If flux or solder is scattered on the surface of P.W.B when soldering, characteristics of this product may be damaged.
 - Cleaning after soldering is not allowed. When cleaning is required this switch should be soldered after the cleaning.
- 6) Avoid the use of the switch under pushed ON condition is continued for a long time.
- 7) There is a possibility the flux from solder paste infiltrates into the body if plenty of solder paste was applied by switch on the P.W.B.

So we recommend to use our proposed land design in order to prevent above problem.

Also please avoid putting additional land by the switch on the P.W.B.



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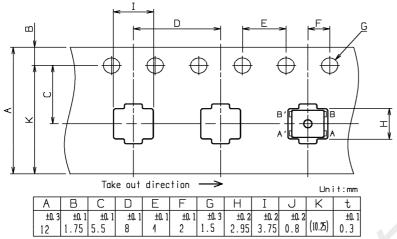
Product orientation direction
(Back side)

Terminal expose area

<u>Circuit diagram</u>

-O A '

7. Packing specification Carrier tape



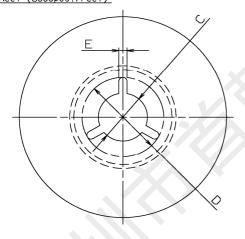
Taping condition: Lack of products in the middle of taping should be one MAX, but total quantity specified in the specifications

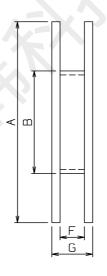
should be secured.

Peeling off strength of top tape: It should be within 0.2N to 1.0N at 165 degree in peeling off angle.

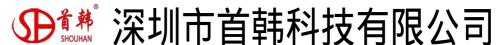
Joint of carrier tape : One joint per one reel may exist.

Reel (8000pcs./reel)





					Un	it:mm
Α	В	С	D	E	F	G
±2	±1	±0.5	±1	±0.5	±1	±1
♦380	ø80	ø13	♦ 21	2	13.5	17.5



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<Prohibitions and precaution for handling>

[Prohibited items on fire and smoking]

- Absolutely avoid use of a product beyond its rated range because doing so may cause a fire. If misuse or abnormal use may result under conditions in which the product is used out of its rated range, take proper measures such as current interruption using a protective circuit.
- The grade of nonflammability for resin used in product is "94HB," which is based on UL94 Standards (flammability test for plastic materials). Prohibit use in a location where a spreading fire may be generated or prepare against a spreading fire.

[For use in equipment for which safety is requested]

- Although care is taken to ensure product quality, inferior characteristics, short circuits, and open circuits are some problems that might be generated. To design an equipment which places maximum emphasis on safety, review the effect of any single fault of a product in advance and perform virtually fail-safe design to ensure maximum safety by:
 - Preparing a protective circuit or a protective device to improve system safety, and equipment.
 - Preparing a redundant circuit to improve system safety so that the single fault of a product does not cause a dangerous situation.

[Attentions required for storage condition]

- When this product is to be stored in the following circumstances and conditions, it may
 affect on the performance deteriorations and solderability etc., avoid storing in the
 following conditions.
 - (1) A place where the temperature is -10°C max., +40°C min. and the humidity is 85% min.
 - (2) In the corrosive gas atmosphere.
 - (3) Long-term storage for 6 months min.
 - (4) A place where the product is exposed to direct sunlight.
- Store in packed condition so that the load stress is not applied.
- Please use this product as soon as possible, our recommendation is within 3 months and the limitation is 6 months.
- If any remainder left after packing is opened, store it with proper moistureproofing and gasproofing, etc.,